

LAMP2013

LPM2013 - The 14th International Symposium on Laser Precision Microfabrication
HPL2013 - The 6th International Symposium on High Power Laser Processing
July 23-26, 2013, TOKI MESSE, NIIGATA, JAPAN

The 6th International Congress on Laser Advanced Materials Processing

DATE: JULY 23-26, 2013
VENUE: TOKI MESSE Niigata Convention Center, Niigata, Japan
ORGANIZER: Japan Laser Processing Society (JLPS)
WEBSITE: <http://www.jlps.gr.jp/lamp/lamp2013>

▶ AIM AND SCOPE

Welcome to join us at LAMP2013!

The International Congress on Laser Advanced Materials Processing (LAMP) deals with science and technology of advanced laser materials processing covering precision microfabrication and high power laser processing. Basically LAMP is held every four years, and the former LAMPs have won the good reputation and popularity as the one of the most excellent international meetings in the world. LAMP2013 is held during July 23-26, 2013, in TOKI MESSE, Niigata, Japan.

LAMP2013 consists of International Symposia on Laser Precision Microfabrication (LPM) and High Power Laser Processing (HPL) and covers hardware as well as software for fundamental research and industrial applications in both micro and macro processing. LAMP2013 is planned as a four-day event with a plenary session, oral and poster sessions, special sessions dealing with topical issues, and the exhibition with inviting most important world authorities in this field. The aim of this congress is to provide a forum for discussion of fundamental aspects of laser-matter interaction, the state-of-the-art of laser materials processing, and topics for the next generation with fundamental scientists, end users and laser manufactures. We expect that LAMP2013 would play an important role not only for understanding fundamental knowledge of laser materials processing but also forecasting future technologies to be developed and the future laser market.

Dr. Koji Sugioka, General Chair, LAMP2013

▶ PRESENTATION TYPES

Oral (20 minutes including 5 minute-Q&A)
Poster & Short Presentation (3 minutes)

▶ ABSTRACT SUBMISSION

DUE DATE: JANUARY 31, 2013

SUBMIT: <http://www.jlps.gr.jp/lamp/lamp2013>

▶ ADVANCE REGISTRATION

ALL PRESENTING AUTHORS are requested to complete Registrations prior to the Early Registration due date, May 1.

▶ PROCEEDINGS OF LAMP2013

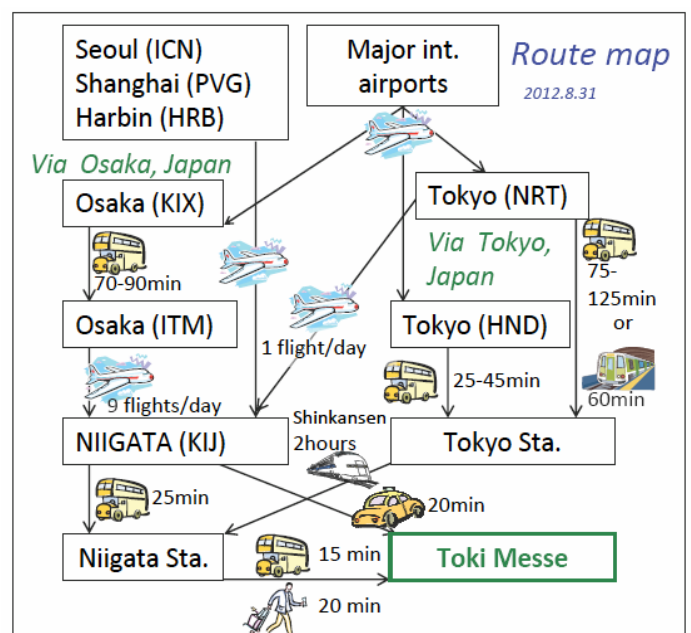
DUE DATE: JULY 23, 2013 (DAY-1)

Proceeding of LAMP2013 will be published online after the congress. Please submit your manuscript(s) through congress website. Manuscript Guidelines and Template can be downloaded from the website.

▶ VENUE

TOKI MESSE Niigata Convention Center, Niigata, Japan
VENUE WEBSITE: <http://www.tokimesse.com/english/>

▶ ACCESS



▶ LPM TOPICS

1. Fundamental aspects
(Dynamics, modeling, simulation, etc.)
2. Process monitoring and control
3. Laser and photochemistry
4. Nanotechnology
5. Laser-based direct-write techniques
6. Ultra-short pulse laser processing
7. VUV laser and X-ray processing
8. Surface treatment
(Texturing, cleaning, annealing, modification, etc.)
9. Advanced laser processing
(Fiber laser, disc laser, FEL, etc.)
10. Micro-patterning and micro-structuring
11. Micro-machining
12. 3-D micro- and nano-fabrication
13. Drilling and cutting
14. Micro-welding and micro-bonding
15. Micro-forming
16. Wafer dicing
17. Marking and trimming
18. Glass/Ceramic processing
19. Packaging and mounting process
20. Lithography
(including EUV source and application)
21. Manufacture of micro devices and systems
22. Film deposition and synthesis of advanced materials (PLD, CVD, etc)
23. Nano- and micro-particles
24. Medical and biological applications
25. Optics and systems for laser microprocessing
26. Laser devices
27. Industrial applications
28. Others
29. Special Session 1: Laser nanofabrication
Session Organizers:
Assoc. Prof. Hong Minghui, Prof. Craig B. Arnold
30. Special Session 2: High speed imaging and time resolved measurements in laser processing
Session Organizer: Prof. Scott A. Mathews
31. Special Session 3: Ultrashort pulsed laser processing toward industrial application
Session Organizer: Prof. Yasuhiro Okamoto, Okayama University, Japan



▶ HPL TOPICS

1. Fundamentals of laser-materials interactions
2. Laser-induced plasma
3. Monitoring and control
4. Modeling and simulation
5. Materials and metallurgical aspects
6. Evaluation of properties (Strength, etc.)
7. High power laser diode
8. Gas laser
9. Solid-state laser (YAG, Fiber, Disk, etc.)
10. Optics
11. Beam delivery system
12. Welding
13. Welding of light metals and alloys
14. Joining of plastics
15. Joining of glasses or ceramics
16. Joining of dissimilar materials
17. Tailored-blank welding
18. Remote welding
19. Hybrid welding
20. Brazing and soldering
21. Drilling and cutting
22. Cleaning
23. Surface modification (Quenching, alloying, etc.)
24. Cladding
25. Rapid prototyping
26. Forming and shaping
27. New and innovative applications
(Sandwich panel, etc.)
28. Applications (Automobiles, ships, trains, airplanes, steel, motors, parts, nuclear fields, etc.)
29. Present status and future prospects
30. Others

▶ JOINT SESSION

Laser additive manufacturing

▶ CONTACT

LAMP2013 Secretariat

Japan Laser Processing Society
c/o Katayama Lab.,
Joining and Welding Research Institute,
Osaka University
11-1 Mihogaoka, Ibaraki,
Osaka 567-0047, Japan
TEL/FAX: +81-6-6879-8642
E-mail: lamp2013@jlps.gr.jp